IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Howard Li, et al.

Application No.: 10/759,801

Group No.: 1753

Filed: January 16, 2004

Examiner: N/A

For: INTEGRATED EQUIPMENT SET FOR FORMING A LOW K DIELECTRIC INTERCONNECT

ON A SUBSTRATE

Mail Stop Petition Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

PETITION TO ACCORD CORRESPONDENCE FILING DATE SHOWN ON EXPRESS MAIL LABEL "DATE-IN" (37 C.F.R. 1.10(c))

1. This is a petition to accord the correspondence in the above-identified Application the "date-in" of January 16, 2004 shown on the Express Mail Label No. EL975550261US.

It is respectfully contended that the date of January 20, 2004 accorded this correspondence by the PTO is incorrect.

- 2. Submitted herewith is the statement of Robert W. Mulcahy as to when the discrepancy was discovered relating to this petition being filed promptly thereafter. 37 C.F.R. 1.10(c)(1).
- 3. Attached is a true copy of the first page of the correspondence which was filed, showing that the number of the Express Mail label was placed thereon prior to mailing. 37 C.F.R. 1.10(c)(2).
- 4. Attached is true copy of the "Express Mail" mailing label showing the "date-in" of January 16, 2004. 37 C.F.R. 1.10(c)(3). Note that our return receipt postcard (copy attached) shows a filing date of January 16, 2004 for this application (U.S. Patent Application Serial No. 10/759,801).

CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. Section 1.8(a))

I hereby certify that, on the date shown below, this correspondence is being:

)

MAILING

FACSIMILE

[x] deposited with the United States Postal Service with sufficient postage as Express Mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

(Express Mail Label No.

[] transmitted by facsimile to the Patent and Trademark Office (703) ______.

Signature

BARBARA HOLT
(type or print name of person certifying)

Date: June 17, 2004

(Petition to Accord Correspondence Filing Date Shown on Express Mail Label "Date-in"--page 1 of 2)

- 5. Other attachments: A copy of the Patent Application Cover Sheet containing Express Mail Certificate.
- 6. The petition fee is paid as follows:

Please charge the petition fee to deposit account no. 50-1074.

A duplicate of this petition is enclosed.

Please charge Account No. 50-1074 for any fee deficiency or credit this account for any overpayment for this petition.

Date:

Robert W. Mulcahy Registration No. 25,436 MAIL STOP PATENT APPLICATION Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Applicant(s): Howard Li et al. Assignee: Applied Materials, Inc.

Title: INTEGRATED EQUIPMENT SET FOR FORMING A LOW K

DIELECTRIC INTERCONNECT ON A SUBSTRATE

Serial No.: unknown Filed: herewith

Docket No.: 6353/P1/LOW K/JW

Enclosed:

X Patent Application Transmittal

X Specification, claims and abstract - 124 pgs.

X Drawings (forty-three pages) Informal

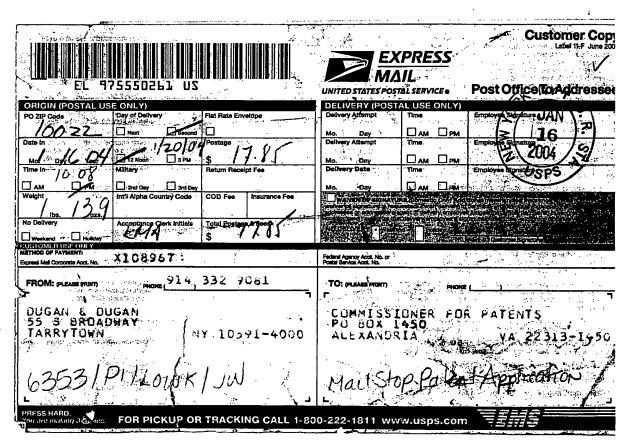
Return Receipt postcards

Dated: January 16, 2004

Express Mail Label No. EL975550261US

15535 U.S. PTO 10/759801





BEST AVAILABLE COPY

APPLICATION FOR UNITED STATES LETTERS PATENT

APPLICANT(S):

HOWARD LI

LEE LUO

ILIAS ILIOPOULOS MICHAEL ARMACOST

TITLE:

INTEGRATED EQUIPMENT SET FOR

FORMING A LOW K DIELECTRIC INTERCONNECT ON A SUBSTRATE

DOCKET NO .:

6353/P1/LOW K/JW

APPLIED MATERIALS, INC.

CERTIFICATE OF MAILING UNDER 37 CFR 1.10

I hereby certify that, on the date shown below, this correspondence is being deposited with the United States Postal Service in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, as "Express Mail Post Office to Addressee" Mailing Label No.: EL975550261US on January 16, 2004

Name of person mailing papers:

Signature

BRIANS M- DEA

Date

DUGAN & DUGAN, P.C. 18 John Street Tarrytown, New York 10591 (914)332-9081 JUN 2 2 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

plicant(s) : Howard Li, et al.

Serial No. : 10/759,801

Filed : January 16, 2004

FOR : INTEGRATED EQUIPMENT SET FOR FORMING A LOW K

DIELECTRIC INTERCONNECT ON A SUBSTRATE

Mail Stop Petition Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

STATEMENT OF PROMPTNESS OF FILING OF PETITION TO CORRECT FILING DATE

Sir:

In accordance with 37 C.F.R. § 1.10 (d)(1), I, Robert W. Mulcahy, state that the discrepancy in the filing date for the above-identified patent application was not discovered until after we received a copy of the Notice to File Missing Parts for this case on or about April 29, 2004. Accordingly, the enclosed Petition is being filed promptly.

Respectfully Submitted

Robert W. Mulcahy

Registration No/25,436

Dated:

INTEGRATED EQUIPMENT SET FOR FORMING A LOW K DIELECTRIC INTERCONNECT ON A SUBSTRATE

This application claims priority from U.S.

Provisional Patent Application Serial No. 60/440,898, filed
January 16, 2003 and is a continuation-in-part of U.S.

Patent Application Serial No. 10/459,194, filed June 11,
2003, which claims priority from U.S. Provisional Patent
Application Serial No. 60/387,835, filed June 11, 2002. All
of the above listed patent applications are hereby
incorporated by reference herein in their entirety.

CROSS REFERENCE TO RELATED APPLICATIONS

This application is related to U.S. Provisional
Patent Application Serial No. 60/323,065, filed September
18, 2001 and titled "INTEGRATED EQUIPMENT SET FOR FORMING AN
INTERCONNECT ON A SUBSTRATE", which is hereby incorporated
by reference herein in its entirety.

This application also is related to U.S.

20 Provisional Patent Application Serial No. 60/333,901, filed
November 28, 2001 and titled "INTEGRATED EQUIPMENT SET FOR
FORMING SHALLOW TRENCH ISOLATION REGIONS", which is hereby
incorporated by reference herein in its entirety.

25 FIELD OF THE INVENTION

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The present invention relates to semiconductor device manufacturing, and more specifically to an integrated equipment set for forming a low K dielectric interconnect on a substrate.

BACKGROUND OF THE INVENTION

A typical integrated circuit contains a plurality of metal pathways that provide electrical power for powering the various semiconductor devices forming the integrated circuit, and that allow these semiconductor devices to